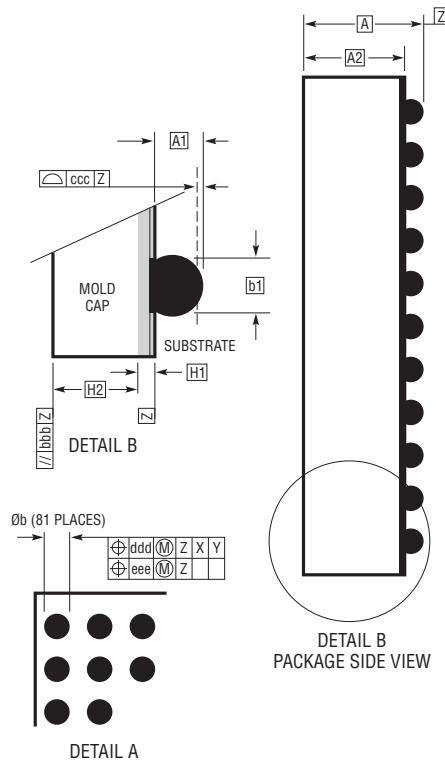
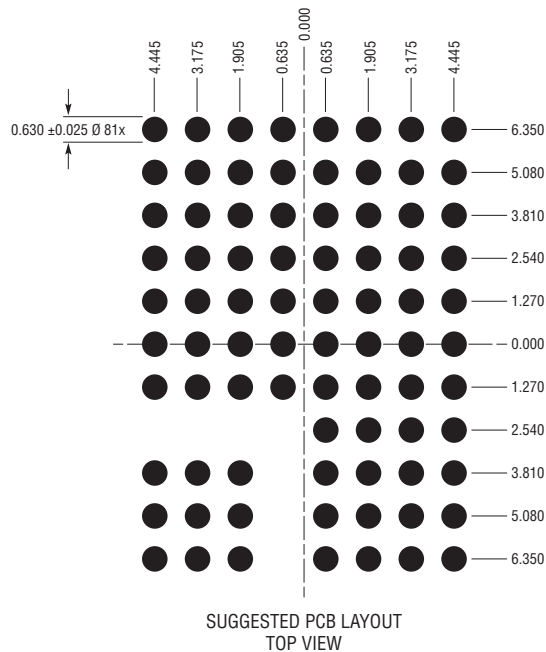
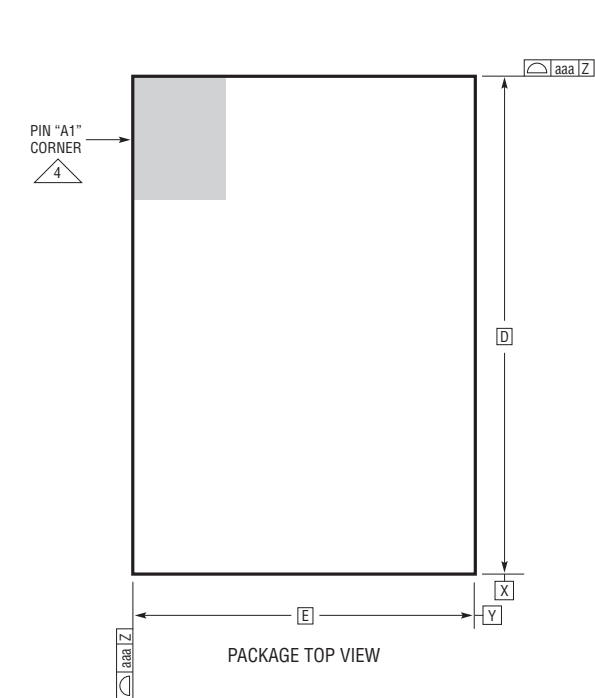
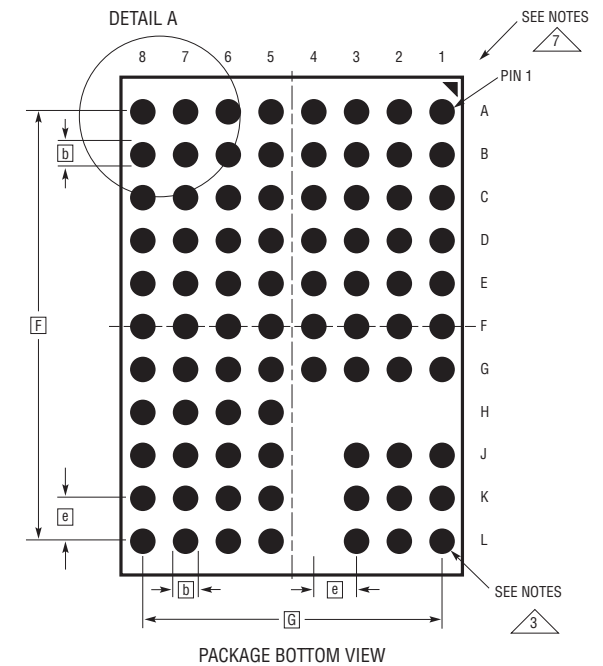


BGA Package
81-Lead (15mm × 11.25mm × 3.42mm)
 (Reference LTC DWG # 05-08-1959 Rev 0)



DIMENSIONS				
SYMBOL	MIN	NOM	MAX	NOTES
A	3.22	3.42	3.62	
A1	0.50	0.60	0.70	
A2	2.72	2.82	2.92	
b	0.60	0.75	0.90	
b1	0.60	0.63	0.66	
D		15.00		
E		11.25		
e		1.27		
F		12.70		
G		8.89		
H1	0.27	0.32	0.37	
H2	2.45	2.50	2.55	
aaa			0.15	
bbb			0.10	
ccc			0.20	
ddd			0.30	
eee			0.15	

TOTAL NUMBER OF BALLS: 81



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
 2. ALL DIMENSIONS ARE IN MILLIMETERS
 3. BALL DESIGNATION PER JESD MS-028 AND JEP95
 4. DETAILS OF PIN #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE
 5. PRIMARY DATUM -Z- IS SEATING PLANE
 6. SOLDER BALL COMPOSITION IS 96.5% Sn/3.0% Ag/0.5% Cu
 7. PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG µModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY

